

# MMBT5088LT1, MMBT5089LT1

MMBT5089LT1 is a Preferred Device

## Low Noise Transistors

### NPN Silicon

#### Features

- Pb-Free Packages are Available

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage MMBT5088 MMBT5089	$V_{CEO}$	30 25	Vdc
Collector-Base Voltage MMBT5088 MMBT5089	$V_{CBO}$	35 30	Vdc
Emitter-Base Voltage	$V_{EBO}$	4.5	Vdc
Collector Current - Continuous	$I_C$	50	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Device Dissipation Alumina Substrate, (Note 2) $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	300 2.4	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

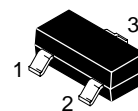
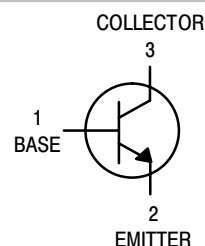
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- FR-5 = 1.0 x 0.75 x 0.062 in.
- Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.



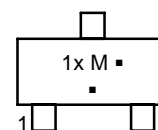
ON Semiconductor®

<http://onsemi.com>



SOT-23 (TO-236)  
CASE 318  
STYLE 6

#### MARKING DIAGRAM



- 1x = Device Code  
 x = Q for MMBT5088LT1  
 x = R for MMBT5089LT1  
 M = Date Code\*  
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### ORDERING INFORMATION

Device	Package	Shipping†
MMBT5088LT1	SOT-23	3,000 / Tape & Reel
MMBT5088LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBT5089LT1	SOT-23	3,000 / Tape & Reel
MMBT5089LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

# MMBT5088LT1, MMBT5089LT1

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Collector–Emitter Breakdown Voltage ( $I_C = 1.0\text{ mAdc}$ , $I_B = 0$ )	MMBT5088 MMBT5089	$V_{(BR)CEO}$	30 25	– –	Vdc
Collector–Base Breakdown Voltage ( $I_C = 100\text{ }\mu\text{Adc}$ , $I_E = 0$ )	MMBT5088 MMBT5089	$V_{(BR)CBO}$	35 30	– –	Vdc
Collector Cutoff Current ( $V_{CB} = 20\text{ Vdc}$ , $I_E = 0$ ) ( $V_{CB} = 15\text{ Vdc}$ , $I_E = 0$ )	MMBT5088 MMBT5089	$I_{CBO}$	– –	50 50	nAdc
Emitter Cutoff Current ( $V_{EB(off)} = 3.0\text{ Vdc}$ , $I_C = 0$ ) ( $V_{EB(off)} = 4.5\text{ Vdc}$ , $I_C = 0$ )	MMBT5088 MMBT5089	$I_{EBO}$	– –	50 100	nAdc
<b>ON CHARACTERISTICS</b>					
DC Current Gain ( $I_C = 100\text{ }\mu\text{Adc}$ , $V_{CE} = 5.0\text{ Vdc}$ )	MMBT5088 MMBT5089	$h_{FE}$	300 400	900 1200	–
( $I_C = 1.0\text{ mAdc}$ , $V_{CE} = 5.0\text{ Vdc}$ )	MMBT5088 MMBT5089		350 450	– –	
( $I_C = 10\text{ mAdc}$ , $V_{CE} = 5.0\text{ Vdc}$ )	MMBT5088 MMBT5089		300 400	– –	
Collector–Emitter Saturation Voltage ( $I_C = 10\text{ mAdc}$ , $I_B = 1.0\text{ mAdc}$ )		$V_{CE(sat)}$	–	0.5	Vdc
Base–Emitter Saturation Voltage ( $I_C = 10\text{ mAdc}$ , $I_B = 1.0\text{ mAdc}$ )		$V_{BE(sat)}$	–	0.8	Vdc
<b>SMALL–SIGNAL CHARACTERISTICS</b>					
Current–Gain — Bandwidth Product ( $I_C = 500\text{ }\mu\text{Adc}$ , $V_{CE} = 5.0\text{ Vdc}$ , $f = 20\text{ MHz}$ )		$f_T$	50	–	MHz
Collector–Base Capacitance ( $V_{CB} = 5.0\text{ Vdc}$ , $I_E = 0$ , $f = 1.0\text{ MHz}$ emitter guarded)		$C_{cb}$	–	4.0	pF
Emitter–Base Capacitance ( $V_{EB} = 0.5\text{ Vdc}$ , $I_C = 0$ , $f = 1.0\text{ MHz}$ collector guarded)		$C_{eb}$	–	10	pF
Small Signal Current Gain ( $I_C = 1.0\text{ mAdc}$ , $V_{CE} = 5.0\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	MMBT5088 MMBT5089	$h_{fe}$	350 450	1400 1800	–
Noise Figure ( $I_C = 100\text{ }\mu\text{Adc}$ , $V_{CE} = 5.0\text{ Vdc}$ , $R_S = 10\text{ k}\Omega$ , $f = 1.0\text{ kHz}$ )	MMBT5088 MMBT5089	NF	– –	3.0 2.0	dB

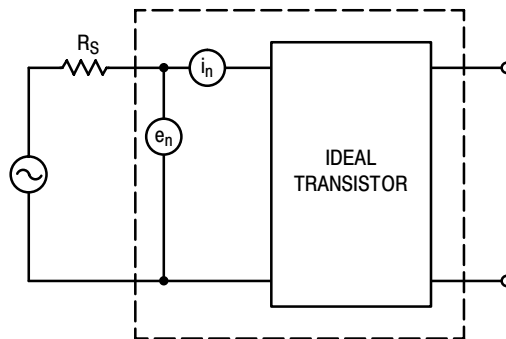


Figure 1. Transistor Noise Model

# MMBT5088LT1, MMBT5089LT1

## NOISE CHARACTERISTICS

( $V_{CE} = 5.0 \text{ Vdc}$ ,  $T_A = 25^\circ\text{C}$ )

### NOISE VOLTAGE

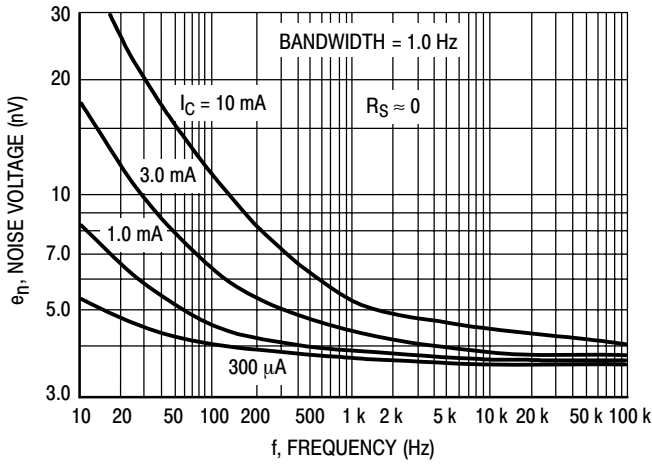


Figure 2. Effects of Frequency

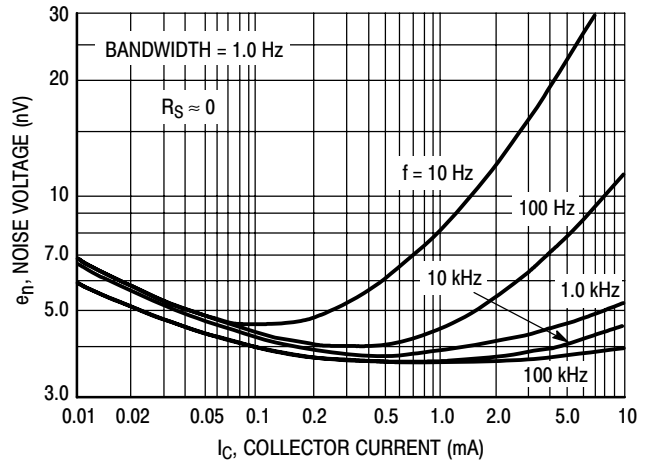


Figure 3. Effects of Collector Current

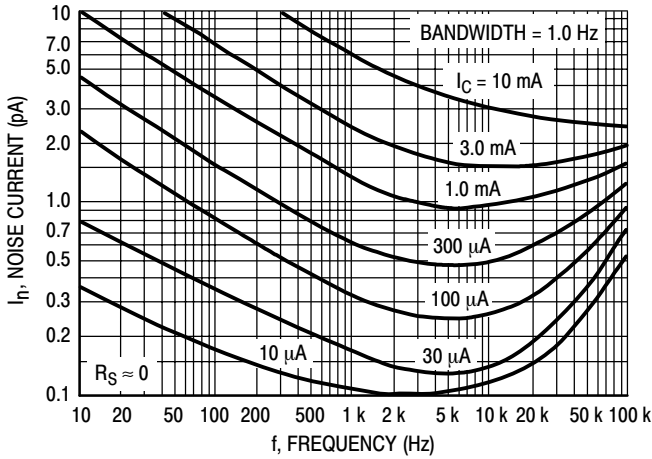


Figure 4. Noise Current

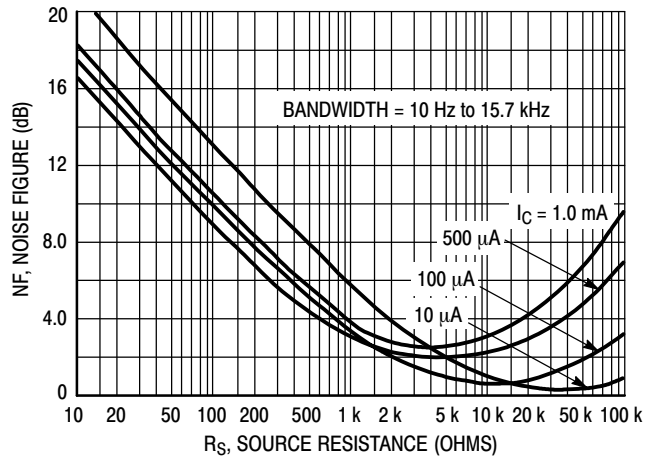


Figure 5. Wideband Noise Figure

### 100 Hz NOISE DATA

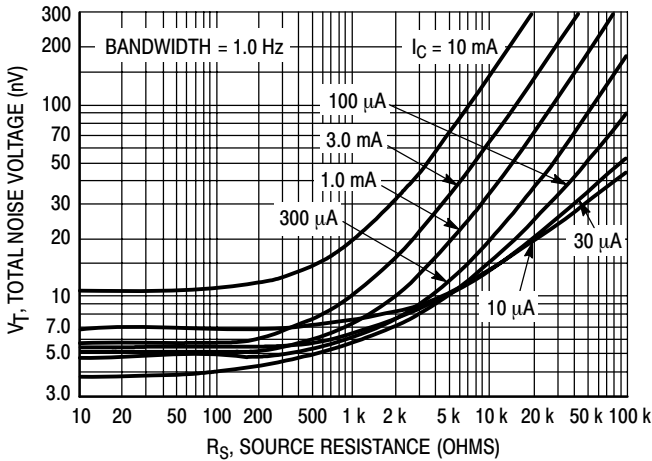


Figure 6. Total Noise Voltage

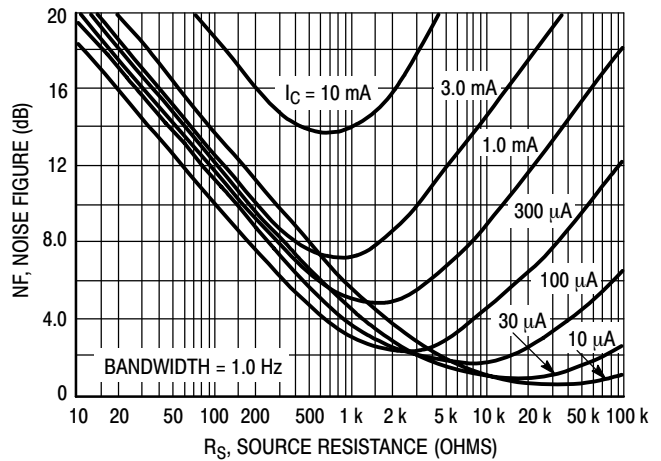


Figure 7. Noise Figure

# MMBT5088LT1, MMBT5089LT1

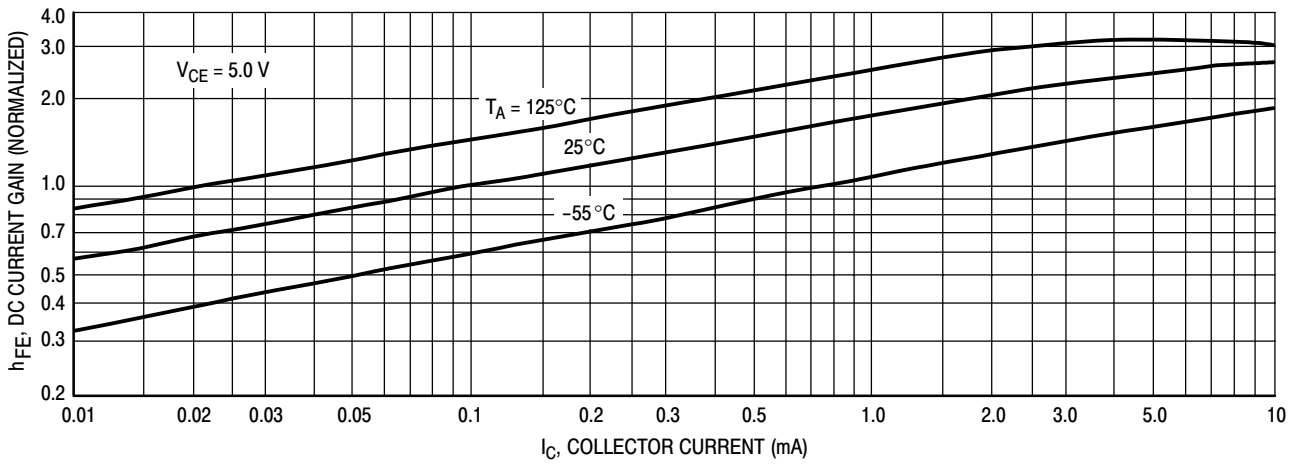


Figure 8. DC Current Gain

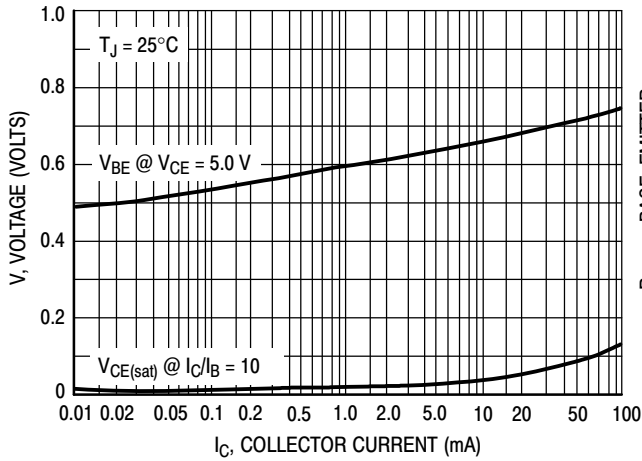


Figure 11. "On" Voltages

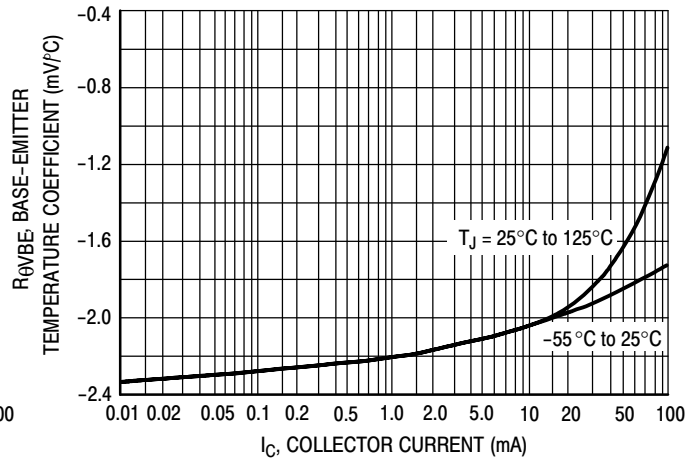


Figure 9. Temperature Coefficients

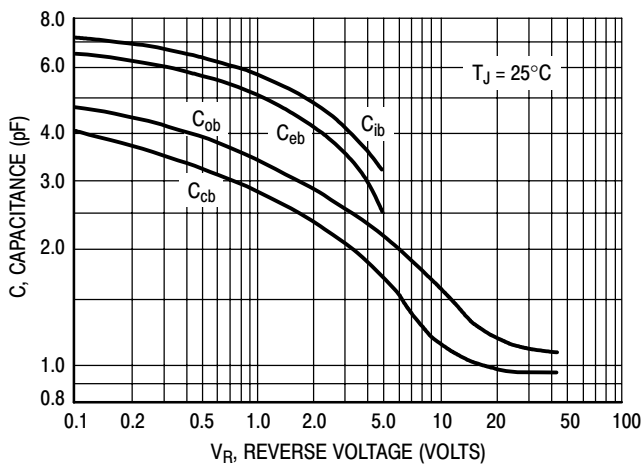


Figure 12. Capacitance

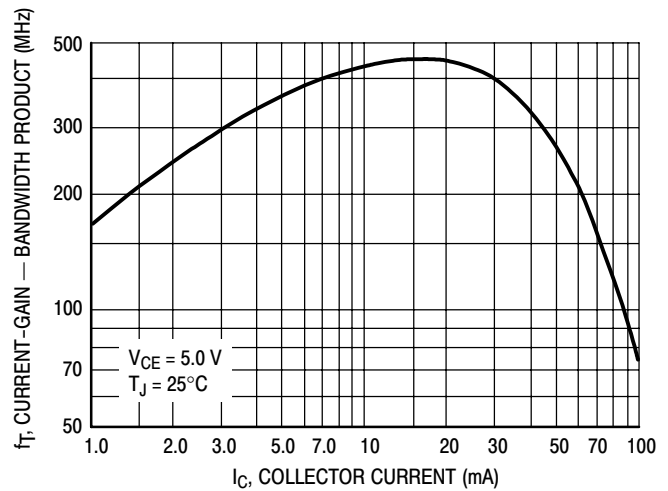
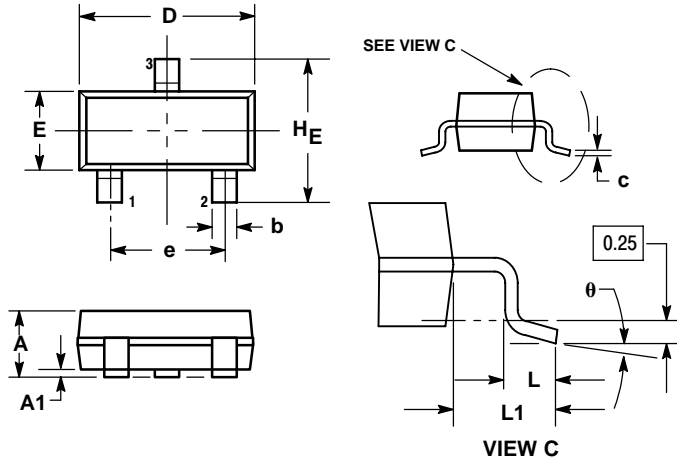


Figure 10. Current-Gain — Bandwidth Product

# MMBT5088LT1, MMBT5089LT1

## PACKAGE DIMENSIONS

SOT-23 (TO-236)  
CASE 318-08  
ISSUE AN



NOTES:

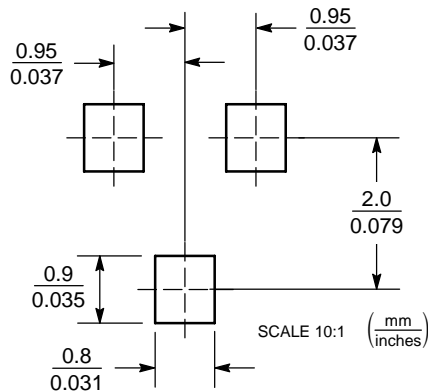
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:

1. BASE
2. EMITTER
3. COLLECTOR

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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